Power MOSFET

–20 V, –3.7 A, 85 m Ω , Single P–Channel, CSP 1.0x1.5x0.65 mm

Features

- Low R_{DS(on)} at Low Gate Voltage
- Chip Scale Packaging
- High Power Density (A/mm²)
- This is a Pb-Free Device

Applications

- Load Switch in Cell Phone, DSC, PMP, GPS, PC's
- Battery Charging Switch

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Rating			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	-20	V
Gate-to-Source Vo	ltage		V_{GS}	±8	V
Continuous Drain Current (Note 1)	Steady State	T _A = 25°C	I _D	-3.7	Α
Continuous Drain Current (Note 2)	Steady State	T _A = 25°C	I _D	-2.9	Α
Power Dissipation (Note 1)	Steady State	T _A = 25°C	P _D	1.5	W
Power Dissipation (Note 2)	Steady State	T _A = 25°C	P _D	0.9	W
Pulsed Drain Current $t_p = 10 \mu$		t _p = 10 μs	I _{DM}	-15	Α
Operating Junction and Storage Temperature			T _J , T _{STG}	-55 to 150	°C
Source Current (Body Diode)			I _S	-1.1	Α
Lead Temperature for Soldering Purposes (IR/Convection)			TL	250	°C

THERMAL RESISTANCE RATINGS

Rating	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	83	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	133	°C/W

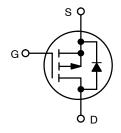
- 1. Surface-mounted on FR4 board using 1 inch sq pad size (Cu area = 1 in sq [2 oz] including traces)
- 2. Surface-mounted on FR4 board using 77.3 sq mm min pad, 2 oz Cu. $\,$



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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX (Note 1)
	85 mΩ @ -4.5 V	
-20 V	123 mΩ @ –2.5 V	0.7.4
	150 mΩ @ –1.8 V	−3.7 A
	200 mΩ @ -1.5 V	



P-Channel MOSFET



6 PIN FLIP-CHIP 1.0 x 1.5 CASE 499BC

PIN CONNECTION AND MARKING DIAGRAM

G S D S S D



воттом т

3141 = Specific Device Code WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping [†]
NTVS3141PT2G	CSP-6 (Pb-Free)	3000/Tape & Reel

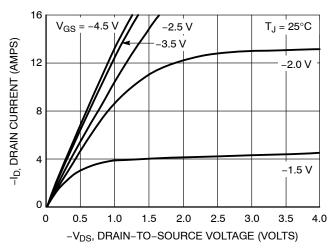
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

$\textbf{MOSFET ELECTRICAL CHARACTERISTICS} \ (T_J = 25^{\circ}C \ unless \ otherwise \ noted)$

Characteristic	Symbol	Test Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS					•	•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-20			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = −250 μA, ref to 25°C		-9.0		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V}, V_{DS} = -20 \text{ V}$			-1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			±0.1	μΑ
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = -250 \mu A$	-0.4	-0.7	-1.2	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J			3.0		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -1.0 \text{ A}$		73	85	mΩ
		$V_{GS} = -2.5 \text{ V}, I_D = -1.0 \text{ A}$		87	123	1
		$V_{GS} = -1.8 \text{ V}, I_D = -1.0 \text{ A}$		107	150	1
		$V_{GS} = -1.5 \text{ V}, I_D = -1.0 \text{ A}$		134	200	1
On to State Drain Current	I _{D(on)}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5.0 \text{ V}$	-10			Α
Forward Transconductance	9 _{FS}	$V_{DS} = -5.0 \text{ V}, I_D = -1.0 \text{ A}$		6.0		S
CHARGES, CAPACITANCES AND GATE I	RESISTANCE					
Input Capacitance	C _{ISS}			840		pF
Output Capacitance	C _{OSS}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = -10 \text{ V}$		155		1
Reverse Transfer Capacitance	C _{RSS}	103 101		120		1
Total Gate Charge	Q _{G(TOT)}			9.0	13	nC
Gate-to-Source Charge	Q_{GS}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -10 \text{ V},$ $I_{D} = -1.0 \text{ A}$		1.0		1
Gate-to-Drain Charge	Q_{GD}	.0		3.0		1
Gate Resistance	R_{G}	f = 1 MHz		9.0		Ω
SWITCHING CHARACTERISTICS, V _{GS} = 4	1.5 V (Note 3)					
Turn-On Delay Time	t _{d(ON)}			7.5	20	ns
Rise Time	t _r	$V_{GS} = -4.5 \text{ V}, V_{DS} = -10 \text{ V},$		9.5	20	1
Turn-Off Delay Time	t _{d(OFF)}	$I_D = -1.0 \text{ A}, R_G = 6.0 \Omega$		35	65	1
Fall Time	t _f			50	80	1
DRAIN-SOURCE DIODE CHARACTERIST	rics					
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 V$, $I_S = -1.1 A$		-0.7	-1.2	V
D	1					
Reverse Recovery Time	t_{RR}	$V_{GS} = 0 \text{ V, di/dt} = 100 \text{ A/}\mu\text{s,}$		37		ns

^{3.} Pulse Test: pulse width \leq 300 μ s, duty cycle \leq 2%

TYPICAL PERFORMANCE CURVES



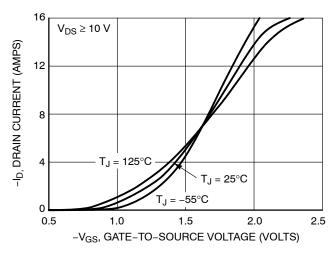
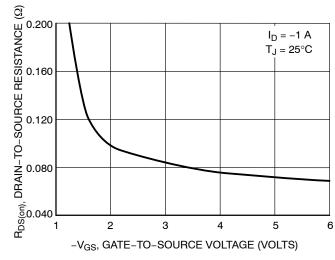


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



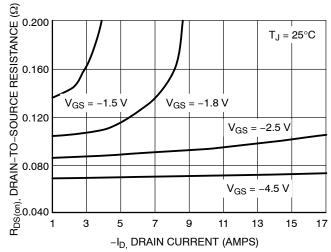
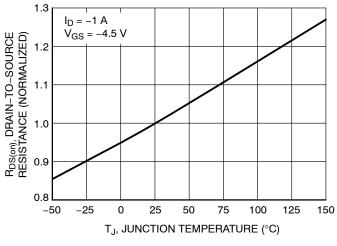


Figure 3. On-Resistance vs. Gate Voltage

Figure 4. On-Resistance vs. Drain Current and Gate Voltage



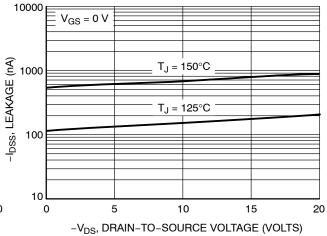


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES

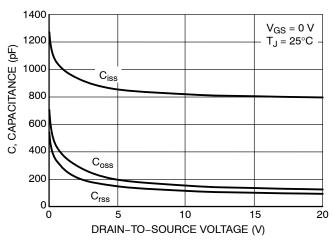


Figure 7. Capacitance Variation

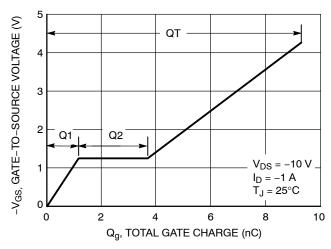


Figure 8. Gate-to-Source Voltage vs. Total Gate Charge

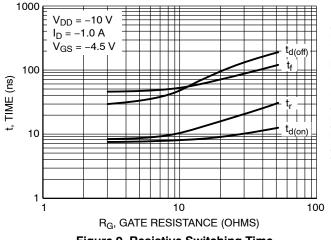


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

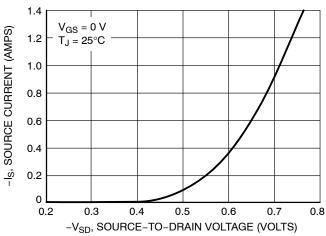


Figure 10. Diode Forward Voltage vs. Current

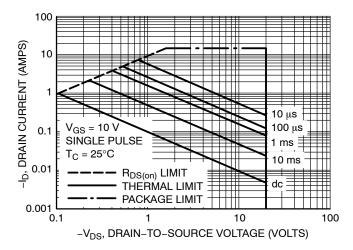


Figure 11. Maximum Rated Forward Biased Safe Operating Area

TYPICAL PERFORMANCE CURVES

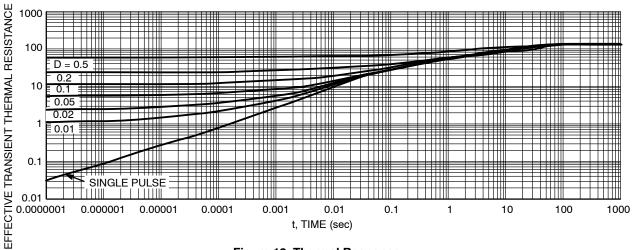
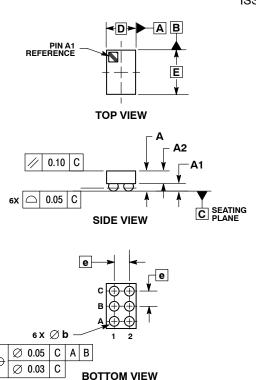


Figure 12. Thermal Response

PACKAGE DIMENSIONS

6 PIN FLIP-CHIP, 1.0x1.5 CASE 499BC **ISSUE A**



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- CONTROLLING DIMENSION: MILLIMETERS.
 COPLANARITY APPLIES TO THE SPHERICAL
 CROWNS OF THE SOLDER BALLS.

	MILLIMETERS			
DIM	MIN	MAX		
Α		0.64		
A1	0.22	0.28		
A2	0.34	0.36		
b	0.29	0.34		
D	0.92	1.00		
E	1.42	1.50		
е	0.50 BSC			

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